step in which the siloxane oligomer is crosslinked while keeping the thermally decomposable polymer remaining in the film, and then conducting a second heating step in which the thermally decomposable polymer is removed.

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Please add the following new claims to the application:

--24. A method for forming a low-permittivity film which comprises applying the composition according to Claim 12 to a substrate to form a composite film comprising the thermally decomposable polymer and the siloxane oligomer evenly compatibilized therewith, and then heating the resulting film to condense the siloxane oligomer and remove the thermally decomposable polymer.

25. A low-permittivity film formed by the method according to Claim 24.

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26. A method for forming a low-permittivity film which comprises applying the composition according to Claim 10 to a substrate to form a composite film comprising the thermally decomposable polymer and the siloxane oligomer evenly compatibilized therewith, and then heating the resulting film to condense the siloxane oligomer and remove the thermally decomposable polymer.

27. A low-permittivity film formed by the method according to Claim 26.

28. A method for forming a low-permittivity film which comprises applying the composition according to Claim 8 to a substrate to form a composite film comprising the thermally decomposable polymer and the siloxane oligomer evenly

compatibilized therewith, and then heating the resulting film to condense the siloxane oligomer and remove the thermally decomposable polymer.

29. A low-permittivity film formed by the method according to Claim 28.

30. A method for forming a low-permittivity film which comprises applying the composition according to Claim 5 to a substrate to form a composite film comprising the thermally decomposable polymer and the siloxane oligomer evenly compatibilized therewith, and then heating the resulting film to condense the siloxane oligomer and remove the thermally decomposable polymer.

31. A low-permittivity film formed by the method according to Claim 30.

A2

32. A method for forming a low-permittivity film which comprises applying the composition according to Claim 12 to a substrate to form a composite film comprising the thermally decomposable polymer and the siloxane oligomer evenly compatibilized therewith, subsequently conducting a first heating step in which the siloxane oligomer is crosslinked while keeping the thermally decomposable polymer remaining in the film, and then conducting a second heating step in which the thermally decomposable polymer is removed.

33. The method according to Claim 32, wherein said first heating step is conducted at a temperature of 80 to 350°C, and wherein said second heating step is conducted at a temperature of 350 to 500°C.

34. A low-permittivity film formed by the method according to Claim 32.

35. A method for forming a low-permittivity film which comprises applying the composition according to Claim 10 to a substrate to form a composite film comprising the thermally decomposable polymer and the siloxane oligomer evenly compatibilized therewith, subsequently conducting a first heating step in which the siloxane oligomer is crosslinked while keeping the thermally decomposable polymer remaining in the film, and then conducting a second heating step in which the thermally decomposable polymer is removed.

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36. The method according to Claim 35, wherein said first heating step is conducted at a temperature of 80 to 350°C, and wherein said second heating step is conducted at a temperature of 350 to 500°C.

37. A low-permittivity film formed by the method according to Claim 35.

38. A method for forming a low-permittivity film which comprises applying the composition according to Claim 8 to a substrate to form a composite film comprising the thermally decomposable polymer and the siloxane oligomer evenly compatibilized therewith, subsequently conducting a first heating step in which the siloxane oligomer is crosslinked while keeping the thermally decomposable polymer remaining in the film, and then conducting a second heating step in which the thermally decomposable polymer is removed.

39. The method according to Claim 38, wherein said first heating step is conducted at a temperature of 80 to 350°C, and wherein said second heating step is conducted at a temperature of 350 to 500°C.

40. A low-permittivity film formed by the method according to Claim 38.

41. A method for forming a low-permittivity film which comprises applying the composition according to Claim 5 to a substrate to form a composite film comprising the thermally decomposable polymer and the siloxane oligomer evenly compatibilized therewith, subsequently conducting a first heating step in which the siloxane oligomer is crosslinked while keeping the thermally decomposable polymer remaining in the film, and then conducting a second heating step in which the thermally decomposable polymer is removed.

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42. The method according to Claim 41, wherein said first heating step is conducted at a temperature of 80 to 350°C, and wherein said second heating step is conducted at a temperature of 350 to 500°C.

43. A low-permittivity film formed by the method according to Claim 41.

44. A low-permittivity film formed by the method according to Claim 39.

45. An electronic part having the low-permittivity film according to Claim 31.

46. An electronic part having the low-permittivity film according to Claim 29.

47. An electronic part having the low-permittivity film according to Claim 27.

48. An electronic part having the low-permittivity film according to Claim 25.

49. An electronic part having the low-permittivity film according to Claim 43.

50. An electronic part having the low-permittivity film according to Claim 40.

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51. An electronic part having the low-permittivity film according to Claim 37.

52. An electronic part having the low-permittivity film according to Claim 34.

53. An electronic part having the low-permittivity film according to Claim 44.--